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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/769,245	01/30/2004	Hsin-Hsien Lu	67,200-1192	8175	
7590 05/19/2006		EXAMINER			
TUNG & ASSOCIATES			KORNAKOV, MICHAIL		
Suite 120 838 W. Long Lake Road			ART UNIT	PAPER NUMBER	
Bloomfield Hills, MI 48302			1746		
			DATE MAILED: 05/19/2000	DATE MAILED: 05/19/2006	

Please find below and/or attached an Office communication concerning this application or proceeding.

Advisory Action Before the Filing of an Appeal Brief

Application No.	Applicant(s)	
10/769,245	LU ET AL.	
Examiner	Art Unit	
Michael Kornakov	1746	

	Wile Haci Northakev				
-The MAILING DATE of this communication appe	ars on the cover sheet w	ith the correspondence ac	ddress		
THE REPLY FILED 05 May 2006 FAILS TO PLACE THIS APPI	LICATION IN CONDITION	FOR ALLOWANCE.			
1. The reply was filed after a final rejection, but prior to or on this application, applicant must timely file one of the follow places the application in condition for allowance; (2) a No a Request for Continued Examination (RCE) in compliance time periods:	ving replies: (1) an amend tice of Appeal (with appea	ment, affidavit, or other evid I fee) in compliance with 37	ence, which CFR 41.31; or (3)		
 a) The period for reply expires 3 months from the mailing date 	of the final rejection.				
b) The period for reply expires on: (1) the mailing date of this A	•	set forth in the final rejection, v	whichever is later. In		
no event, however, will the statutory period for reply expire la					
Examiner Note: If box 1 is checked, check either box (a) or (TWO MONTHS OF THE FINAL REJECTION. See MPEP 7		HEN THE FIRST REPLY WAS	FILED WITHIN		
Extensions of time may be obtained under 37 CFR 1.136(a). The date have been filed is the date for purposes of determining the period of exunder 37 CFR 1.17(a) is calculated from: (1) the expiration date of the set forth in (b) above, if checked. Any reply received by the Office later may reduce any earned patent term adjustment. See 37 CFR 1.704(b) NOTICE OF APPEAL	on which the petition under 3 tension and the corresponding shortened statutory period for than three months after the n	g amount of the fee. The appro reply originally set in the final C	priate extension fee Office action; or (2) as		
The Notice of Appeal was filed on A brief in comp	liance with 37 CFR 41.37	must be filed within two mor	nths of the date of		
filing the Notice of Appeal (37 CFR 41.37(a)), or any external a Notice of Appeal has been filed, any reply must be filed AMENDMENTS	nsion thereof (37 CFR 41.3	37(e)), to avoid dismissal of			
3. The proposed amendment(s) filed after a final rejection,			because		
(a) They raise new issues that would require further co		(see NOTE below);			
 (b) ☐ They raise the issue of new matter (see NOTE belo (c) ☐ They are not deemed to place the application in bet 	• •	erially reducing or simplifyin	g the issues for		
appeal; and/or	narranandina numbar af f	inally rejected eleims			
(d) They present additional claims without canceling a NOTE: (See 37 CFR 1.116 and 41.33(a)).	corresponding number of t	many rejected claims.			
4. The amendments are not in compliance with 37 CFR 1.12	21. See attached Notice of	Non-Compliant Amendmer	nt (PTOL-324).		
5. Applicant's reply has overcome the following rejection(s)		, , , , , , , , , , , , , , , , , , ,	,		
6. Newly proposed or amended claim(s) would be all		eparate, timely filed amendr	ment canceling the		
non-allowable claim(s). 7. For purposes of appeal, the proposed amendment(s): a)	will not be entered, or I	o) ☐ will be entered and ar	n explanation of		
how the new or amended claims would be rejected is prov		.,			
The status of the claim(s) is (or will be) as follows:					
Claim(s) allowed: Claim(s) objected to:					
Claim(s) rejected: <u>1-3,5,11-13,15,16 and 21-23</u> .					
Claim(s) withdrawn from consideration:					
AFFIDAVIT OR OTHER EVIDENCE					
8. The affidavit or other evidence filed after a final action, bu because applicant failed to provide a showing of good and was not earlier presented. See 37 CFR 1.116(e).					
9. The affidavit or other evidence filed after the date of filing entered because the affidavit or other evidence failed to o showing a good and sufficient reasons why it is necessary	vercome all rejections und	ler appeal and/or appellant i	fails to provide a		
10. The affidavit or other evidence is entered. An explanation	•	· · · · · · · · · · · · · · · · · · ·			
REQUEST FOR RECONSIDERATION/OTHER 11. ☑ The request for reconsideration has been considered bu	t does NOT place the appl	ication in condition for allow	ance because:		
See Continuation Sheet. 12 □ Note the attached Information Disclosure Statement(s)	PTO/SB/08 or PTO-1449)	Paner No(s)			
12. ☐ Note the attached Information Disclosure Statement(s). (PTO/SB/08 or PTO-1449) Paper No(s) 13. ☐ Other:					
	*	Michael Kornak	ov		
	. /	Primary Examine			
<i>/</i>	4. COONA COL	Art Unit: 1746			

U.S. Patent and Trademark Office PTOL-303 (Rev. 7-05) Continuation of 11. does NOT place the application in condition for allowance because: Continuation of 11. does NOT place the application in condition for allowance because: of the reasons set forth in the final office action on the merits. Applicants argue that the reference does not teach applying said surfactant composition solution to said wafer surface after at least one of said plurality of polishing steps to render said wafer surface hydrophilic; and then rinsing said wafer surface. In response to this the Examiner urges and maintains his position that the reference either expressly or inherently teaches the method of cleaning a wafer having a metal, such as copper on the surface (0048, 0049), the process includes at least two CMP procedures, wherein after the first CMP process, the wafer is rinsed with surfactant (0047). By the virtue of surfactant action, the surface of the wafer inherently acquires hydrophilicity. A third CMP process may be performed, wherein the barrier layer comprising nitride (0050) is removed, than the spraying of surfactant is performed, and the deionized water rinse is completed (0050). The method includes polishing of a surface of the semiconductor wafer that includes low-K dielectric material (0056). Therefore, all the limitations as instantly presented are either expressly or inherently met by the applied reference. The rejection under 35 USC 103 is maintained as per reasons of record . .